Printed Circuit Board (PCB) First Article (FA) Report

Customer : **0**

Customer P/N: 0

Product No.: 0

QTY: 0

Date Code: 0

S/N	Description	CHECK
1	Certificate of Compliance	√
2	Final Product Inspection Report	√
3	Hole Size & Outline Dimension Report	√
4	Micro-section Report	√
5	Solderability Test Report	√
6	Thermal Stress Test Report	√
7	E-Test Report	√
8	Ionic Contamination Report	√
9	RoHS Compliance Statement	√

Final Disposal: **Accept** ■ **Reject** □

Checked By: _____ **Date:** _____

Approved By: _____ **Date:** _____

Certificate of Compliance

Customer Name:			
Customer P/N:			
PO Number:			
Product No.:			
Shipped QTY:			
QTY (pcs):		/	/
Date Code:		/	/

Certification Items

This certificate is to serve as proof that all requirements of customer's specification are maintained in fabrication of this including the followings.

1 All PCBs shipped comply with purchasing specifications and/or drawings.

2 Where no spec in the drawings and/or materials are given, IPC specs apply.

3 Laminate and prepreg used in fabrication are in compliance with IPC-4101.

4 All finish boards have been 100% electrically tested and passed.

5 Finish boards meet all requirements of UL 796 and flammability rating 94V0.

6 Non-operational printed circuit board and packing material should be discarded according to local laws

All information listed on this document is hereby certified in writing to be true.

Authorized Signature:	**Date:**
Printed Name:	**Title:** **Final Quality Assurance Supervisor**
Quality Department Stamp	

Final Product Inspection Report

Country of Origin: CHINA		Cust PN: 0		Drawing No.: 0	
Product No.: 0		Lot Size: 0		AQL LEVEL II 0.40	
		Flammability Grade: 94V0		Sample size:	
Item	Description	Specification	Actual	Acc	Rej
(A) Visual		AQL II 0.40	YES	√	
(B) Material					
1	Raw Material			√	
2	Core Thickness			√	
3	Copper Thickness (OZ)			√	
(C) Marking & Circuitry					
1	Min Line Width			√	
2	Min Spacing			√	
3	Front & Back registration			√	
(D) Surface treatment thickness					
1	Process	/	/	/	
2	HAL	/	/	/	
3	lead-Free HASL	/	/	/	
4	Immersion Gold Ni			/	
	Immersion Gold Au			/	
5	Immersion Silver	/	/	/	
6	Immersion Tin	/	/	/	
7	Gold Finger Ni	/	/	/	
	Gold Finger Au	/	/	/	
8	OSP	/	/	/	
(E) Soldermask & Component Marking					
1	S/M Material & Color				
	Applied on				
2	S/M Tape Test/Solvent Test				
3	S/M Registration				
4	C/M Material (Color)				
	Applied on				
5	C/M Tape Test / Solvent Test				
6	C/M Registration				
(F) Profile					
1	Overall Thickness				
2	Bow & Twist (max)				
(G) Functional Test					
1	Electrical Test	No Open/Short	YES	√	

(H) Hole Size & Outline Dimension Report

Finished Hole Size(Unit:mm)

Code	Qty	Requirement	Actual	Acc/ Rej	Remarks	Code	Qty	Requirement	Actual	Acc/ Rej	Remarks
1											
2											
3											
4											
5											

Dimension Measurement(Unit:inch)

No.	Requirement	Tolerance	Actual	Acc/ Rej
1				ACC
2				ACC
3				ACC
4				ACC
5				ACC
6				ACC
7				ACC
8				ACC
9				ACC
10				ACC
11				ACC
12				ACC
13				ACC
14				ACC
15				ACC
16				ACC
17				ACC
18				ACC
19				ACC
20				ACC
21				ACC
22				ACC
23				ACC
24				ACC
25				ACC
26				ACC
27				ACC
28				ACC
29				ACC
30				ACC
31				ACC
32				ACC
33				ACC
34				ACC
35				ACC
36				ACC

Dimension Measurement(Unit:mm)

No.	Requirement	Tolerance	Actual	Acc/ Rej

0.3048

V-cut measure (Unit:mm)

	Items	Requirement	Actual	Acc/Rej
1	Angle			ACC
	Thickness			ACC

Beveling measure (Unit:mm)

	Items	Requirement	Actual	Acc/Rej
2	Angle	/	/	/
	Deepness	/	/	/

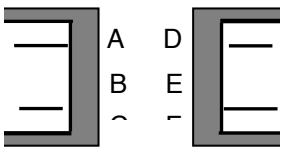
Micro-section Report

Customer Name	0	Customer P/N	0
Product P/N	0	Sample Size	1PCS
Remark			

Hole Wall Microsection Data(Unit:μm)

Request	Minimum:						Average:/	
No.	A	B	C	D	E	F	minimum	Average
1							0.0	
2								
Result	ACC							

HOLE- WALL COPPER THICKNESS



Blind Hole wall copper Data(Unit:μm)

Request	Minimum: /						Average: /	
No.	A	B	C	D	E	F	minimum	Average:
1	/						0.0	
2	/							
Result	/							

Buried Hole wall copper Data(Unit:μm)

Request	Minimum: /						Average: /	
No.	A	B	C	D	E	F	minimum	Average:
1	/						0.0	
2	/							
Result	/							

Copper Thickness Data(Unit:μm)

Layer	Base copper	Finish Copper Requirement(From Customer or IPC)	Actual	Result
Top Side				ACC
L2				ACC
L3				ACC
Bottom Side				ACC

Soldermask Thickness Data(Unit:μm)

Speciment Location	Request	Actual	Result
Circuit Surface			ACC
Circuit Corner			ACC

Dielectric Measurement Record (Unit:μm)

Layer	Request	Actual	Result
L1-L2			ACC
L2-L3			ACC
L3-L4			ACC

Disposition:

ACC ■ REJ □

Solderability Test Report

General Information			
Customer Name	0	Customer P/N	0
Product P/N	0	Sample Size	1PCS
Remark			

Test Method: Follow IPC-TM-650 Standard

Solderability test

Condition	Temperature	Time	Result		Accept/Reject	Remark
		4S±0.5S	Blow-hole	Non-Wetting		
			NO	NO	ACC	

Final Conclusion:

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Thermal Stress Test Report

General Information			
Customer Name	0	Customer P/N	0
Product P/N	0	Sample Size	1PCS
Remark			

Test Method: Follow IPC-TM-650 Standard

Thermal stress test

Condition	Temperature	Time	Result						Acc/Rej
	288°C	10S,3Times	Discolor	Delamination	Measling	S/M peel off	Blister	Crack	
			NO	NO	NO	NO	NO	NO	ACC

Final Conclusion:

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E-Test Report

General Information			
Customer Name	**0**	**Customer P/N**	**0**
Product P/N	**0**	**Remark**	

Test Method:

Test Qty	CS	Pass Qty	CS	Pass Rate	100%

Test condition

A	**Testing coverage rate**	
B	**Voltage**	
C	**Continuity Test**	
D	**Insulation Test**	

This E-Test Report is to certify the electrical test has been performed per IPC-9252, Class II requirements. All product that passed testing has met and or exceeded Class II as defined by IPC-9252. Actual test method, conditions, and results are shown above.

Ionic Contamination Report

General Information			
Customer Name	**0**	**Customer P/N**	**0**
Product P/N	**0**	**Sample Size**	**1PCS**
PCB Description			

Test Method : Follow IPC-TM-650 Standard

Test content

Items	Data	Unit		Remark
Request				
Actual result				

Final Conclusion:

RoHS Compliance Statement

General Information			
Customer Name	**0**	**Customer P/N**	**0**
Product P/N	**0**	**PO Number**	
Shipped Quantity	**0**	**Surface Treatment**	/

Statement of Declaration

Shenzhen Global Circuits is fully aware of the need to reduce the environmental impact of our products and to meet the requirements of EU directive 2011/65/EU and Amendment 2015/863.

The above mentioned part number meet the RoHS directive as it does not exceed the allowed limits for the restricted substances listed below:

No.	Substance	Control Limit
1	Lead (Pb)	Under 1000ppm
2	Mercury (Hg)	Under 1000ppm
3	Cadmium (Cd)	Under 100ppm
4	Hexavalent Chromium	Under 1000ppm
5	Polybrominated biphenyls (PBB)	Under 1000ppm
6	Polybrominated diphenyl ethers (PBDE)	Under 1000ppm
7	Bis(2-ethylhexyl) phthalate (DEHP)	Under 1000ppm
8	Butyl benzyl phthalate (BBP)	Under 1000ppm
9	Dibutyl phthalate (DBP)	Under 1000ppm
10	Diisobutyl phthalate (DIBP)	Under 1000ppm

Signature	
Authorized Signature:	**Date:**
Printed Name:	**Title:** **Final Quality Assurance Supervisor**
Quality Department Stamp	

Impedance Test Report

General Information			
Customer Name		**Customer P/N**	
Product P/N		**Sample Size**	
Test Date			

Test Result

NO.	Request (Ω)	Layer	Referance layer	Line width (mil)	Line space (mil)	Actual test data			Accept/Reject
						Max(Ω)	Min(Ω)	Average(Ω)	
1									ACC
2									ACC
3									ACC
4									ACC

Final Conclusion: